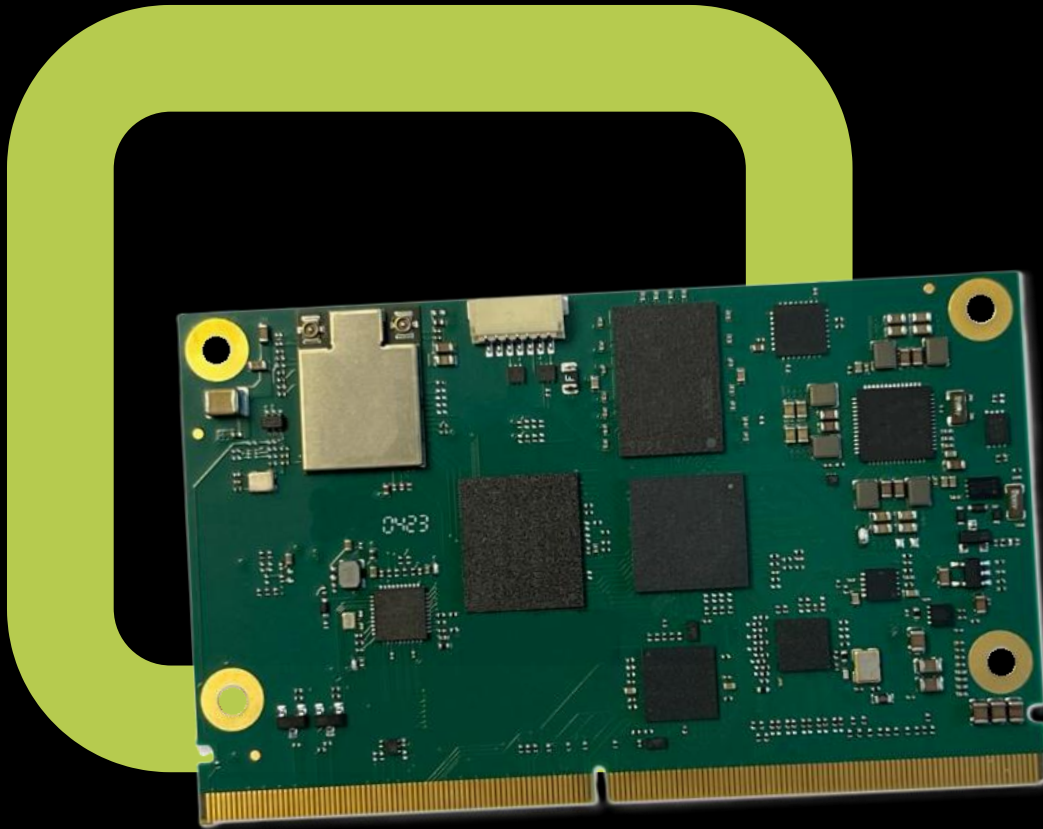


SMARC[®]

User Manual



SOM- SMARC- MX93

SMARC[®] Rel. 2.1.1 compliant
module with NXP i.MX 93
Applications Processors

REVISION HISTORY

Revision	Date	Note	Rif
1.0	28 th November 2024	First official release	SO

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For further information on this module or other SECO products, but also to get the required assistance for any and possible issues, please contact us using the dedicated web form available at <http://www.seco.com> (registration required).

Our team is ready to assist.

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INTRODUCTION

- Warranty
- Information and assistance
- RMA number request
- Safety
- Electrostatic Discharges
- RoHS compliance
- Terminology and definitions
- Reference specifications



1.1 Warranty

This product is subject to the Italian Law Decree 24/2002, acting European Directive 1999/44/CE on matters of sale and warranties to consumers.

The warranty on this product lasts for 1 year.

Under the warranty period, the Supplier guarantees the buyer assistance and service for repairing, replacing or credit of the item, at the Supplier's own discretion.

Shipping costs that apply to non-conforming items or items that need replacement are to be paid by the customer.

Items cannot be returned unless previously authorised by the supplier.

The authorisation is released after completing the specific form available on the website <https://www.seco.com/us/support/online-rma.html> (RMA Online). The RMA authorisation number must be put both on the packaging and on the documents shipped with the items, which must include all the accessories in their original packaging, with no signs of damage to, or tampering with, any returned item.

The error analysis form identifying the fault type must be completed by the customer and has must accompany the returned item.

If any of the above-mentioned requirements for RMA is not satisfied, the item will be shipped back, and the customer will have to pay any and all shipping costs.

Following a technical analysis, the supplier will verify if all the requirements, for which a warranty service applies, are met. If the warranty cannot be applied, the Supplier will calculate the minimum cost of this initial analysis on the item and the repair costs. Costs for replaced components will be calculated separately.



Warning!

All changes or modifications to the equipment not explicitly approved by SECO S.p.A. could impair the equipment's functionality and could void the warranty

1.2 Information and assistance

What do I have to do if the product is faulty?

SECO S.p.A. offers the following services:

- SECO website: visit <http://www.seco.com> to receive the latest information on the product. In most of the cases it is possible to find useful information to solve the problem.
- SECO Sales Representative: the Sales Rep can help to determine the exact cause of the problem and search for the best solution.
- SECO Help-Desk: contact SECO Technical Assistance. A technician is at disposal to understand the exact origin of the problem and suggest the correct solution.

E-mail: technical.service@seco.com

Fax (+39) 0575 350210

- Repair center: it is possible to send the faulty product to the SECO Repair Centre. In this case, follow this procedure:
 - Returned items must be accompanied by a RMA Number. Items sent without the RMA number will be not accepted.
 - Returned items must be shipped in an appropriate package. SECO is not responsible for damages caused by accidental drop, improper usage, or customer neglect.

Note: Please have the following information before asking for technical assistance:

- Name and serial number of the product;
- Description of Customer's peripheral connections;
- Description of Customer's software (operating system, version, application software, etc.);
- A complete description of the problem;
- The exact words of every kind of error message encountered.

1.3 RMA number request

To request an RMA number, please visit SECO's website. On the home page, please select "RMA Online" and follow the procedure described.

An RMA Number will be sent within 1 working day (only for on-line RMA requests).

1.4 Safety

The SOM-SMARC-MX93 module uses only extremely low voltages.

While handling the board, please use extreme caution to avoid any kind of risk or damages to electronic components.



Always switch the power off, unplug the power supply unit and wait until the unit has cooled down, before handling the board and/or connecting cables or other boards.

Avoid using metallic components - like paper clips, screws and similar - near the board when connected to a power supply, to avoid short circuits due to unwanted contacts with other board components.

If the board has become wet, never connect it to any external power supply unit or battery.

1.5 Electrostatic Discharges

The SOM-SMARC-MX93 module, like any other electronic product, is an electrostatic sensitive device: high voltages caused by static electricity could damage some or all the devices and/or components on-board.



Whenever handling any of these boards, ground yourself through an anti-static wrist strap. Placement of the board on an anti-static surface is also highly recommended.

1.6 RoHS compliance

The SOM-SMARC-MX93 module is designed using RoHS compliant components and is manufactured on a lead-free production line. It is therefore fully RoHS compliant.

1.7 Safety Policy

In order to meet the safety requirements of IEC 62368-1:2018 standard for Audio/Video, information and communication technology equipment, the SOM-SMARC-MX93-Module shall be:

- used exclusively on SMARC 2.1 fully compliant carrier boards;
- connections from or to the module have to be compliant to ESI requirements;
- used inside a fire enclosure made of non-combustible material or V-1 material (the fire enclosure is not necessary if the maximum power supplied to the module never exceeds 100 W, even in worst-case fault);
- used along with CPU heat spreader/heatsinks designed according to the thermal characteristics indicated in the par. 2.2 and to the mechanical characteristics indicated in par.2.4.

The manufacturer which includes a SOM-SMARC-MX93 module in his end-user product shall:

- Install the device inside an enclosure compliant with all applicable IEC 62368-1 requirements;
- Prevent children from accessing the board;
- Prescribe temperature and humidity range for operating, transport and storage conditions;
- verify the compliance with B.2 and B.3 clauses of the IEC 62368-1 standard when the module works in its own final operating condition;
- provide an instructional safeguard against thermal injuries, according to clause 9.5.2 of the above-mentioned standard. This instructional safeguard must be placed both on end-user product's User Manual and on the products itself (Danger Label IEC 60417-5041, it must be placed near the CPU or its heatsink);
- When an heatsink with FAN is used, then the FAN should be managed with signals made available by SMARC Card Edge Connector of the SOM-SMARC-MX93 module. Its electrical characteristics must be compliant to the requirements of SMARC Rel.2.1 standard.

1.8 Terminology and definitions

API	Application Program Interface, a set of commands and functions that can be used by programmers for writing software for specific Operating Systems
BTLE	Bluetooth Low Energy, a wireless personal area network technology
CAN Bus	Controller Area network, a protocol designed for in-vehicle communication
CSI2 processor	MIPI Camera Serial Interface, 2nd generation standard regulating communication between a peripheral device (camera) and a host
DDC	Display Data Channel, a kind of I2C interface for digital communication between displays and graphics processing units (GPU)
DDR	Double Data Rate, a typology of memory devices which transfer data both on the rising and on the falling edge of the clock.
DVI	Digital Visual interface, a type of display video interface
FFC/FPC	Flexible Flat Cable / Flat Panel Cable
GBE	Gigabit Ethernet
Gbps	Gigabits per second
GND	Ground
GPI/O	General purpose Input/Output
HDMI	High-Definition Multimedia Interface, a digital audio and video interface
I2C Bus	Inter-Integrated Circuit Bus, a simple serial bus consisting only of data and clock line, with multi-master capability
I2S	Inter-Integrated Circuit Sound, an audio serial bus protocol interface developed by Philips (now NXP) in 1986
LPDDR4	Low-Power Double Data Rate Synchronous Dynamic Random Access Memory, 4 th generation
LVDS	Low Voltage Differential Signalling, a standard for transferring data at very high-speed using inexpensive twisted pair copper cables, usually used for video applications
Mbps	Megabits per second
MIPI	Mobile Industry Processor Interface alliance
MMC/eMMC	MultiMedia Card / embedded MMC, a type of memory card, having the same interface as the SD card. The eMMC is the embedded version of the MMC. They are devices that incorporate the flash memories on a single BGA chip.
N.A.	Not Applicable
N.C.	Not Connected
OpenGL	Open Graphics Library, an Open Source API dedicated to 2D and 3D graphics
OpenVG	Open Vector Graphics, an Open Source API dedicated to hardware accelerated 2D vector graphics

OTG the port.	On-the-Go, a specification that allows to USB devices to act indifferently as Host or as a Client, depending on the device connected to
PCI-e	Peripheral Component Interface Express
PWM	Pulse Width Modulation
PWR	Power
RGMII	Reduced Gigabit Reduced Media Independent Interface, a standard interface between the Ethernet Media Access Control (MAC) and the Physical Layer (PHY)
SD	Secure Digital, a memory card type
SDIO	Secure Digital Input/Output, an evolution of the SD standard that allows the use of the same SD interface to drive different Input/Output devices, like cameras, GPS, Tuners and so on.
SM Bus	System Management Bus, a subset of the I2C bus dedicated to communication with devices for system management, like a smart battery and other power supply-related devices.
SPI	Serial Peripheral Interface, a 4-Wire synchronous full-duplex serial interface which is composed of a master and one or more slaves, individually enabled through a Chip Select line.
TBM	To be measured
TMDS	Transition-Minimized Differential Signalling, a method for transmitting high speed serial data, normally used on DVI and HDMI interfaces
TTL	Transistor-transistor Logic
USB	Universal Serial Bus
uSDHC	Ultra Secure Digital Host Controller

1.9 Reference specifications

Here below it is a list of applicable industry specifications and reference documents.

Reference	Link
CAN Bus	http://www.bosch-semiconductors.de/en/ubk_semiconductors/safe/ip_modules/can_literature/can_literature.html
CSI	http://www.mipi.org/specifications/camera-interface
DDC	http://www.vesa.org
Fast Ethernet	http://standards.ieee.org/about/get/802/802.3.html
HDMI	http://www.hdmi.org/index.aspx
I2C	http://www.nxp.com/documents/other/UM10204_v5.pdf
I2S	https://www.sparkfun.com/datasheets/BreakoutBoards/I2SBUS.pdf
LVDS	http://www.ti.com/ww/en/analog/interface/lvds.shtml and http://www.ti.com/lit/ml/snla187/snla187.pdf
MIPI	http://www.mipi.org
MMC/eMMC	http://www.jedec.org/committees/jc-649
NXP i.MX 8M Plus processor	i.MX 93 Cortex-A55/M33 NXP Semiconductors
OpenGL	http://www.opengl.org
OpenVG	http://www.khronos.org/openvg
PCI Express	http://www.pcisig.com/specifications/pciexpress
SMARC Design Guide 2.0	https://www.sget.org/fileadmin/user_upload/SMARC_DG_V2.pdf
SMARC Hardware Specification 2.1.1	https://sget.org/wp-content/uploads/2020/05/SMARC_V211.pdf
SD Card Association	https://www.sdcard.org/home
SDIO	https://www.sdcard.org/developers/overview/sdio
SM Bus	http://www.smbus.org/specs
TMDS	http://www.siliconimage.com/technologies/tmids
USB 2.0 and USB OTG	http://www.usb.org/developers/docs/usb_20_070113.zip

Chapter 2. OVERVIEW

- Introduction
- Technical Specifications
- Electrical Specifications
- Mechanical Specifications
- Supported Operating Systems
- Block Diagram



2.1 Introduction

SOM-SMARC-MX93 is a SMARC Rel. 2.1 compliant module with NXP i.MX 93 Applications Processors. Featuring multicore and real-time processing together with neural networks acceleration and a vision system. It is a scalable solution designed by SECO for home automation, transportation, digital signage and vending machines, and applicable to scenarios requiring advanced security, connectivity, multimedia and real-time response.

The module offers a very high level of integration, both for all most common used peripherals in the ARM domain and for bus interfaces typically used in the x86 domain, like PCI-Express

Presented in the SMARC ("Smart Mobility ARChitecture") form factor, offering the computing abilities of a standard board, with the possibilities of combining with a ready-to-use carrier board like the SECO CSM-B79 or customised carrier board.

For external interfacing to standard devices, a carrier board with a 314-pin MXM connector is needed. This board will implement all the routing of the interface signals to external standard connectors, as well as the integration of other peripherals/devices not already included in SOM-SMARC-MX93 module.

2.2 Technical Specifications

Processors

NXP i.MX 93[®] Family:

- Dual – 2x Cortex[®]-A55 cores 1.7GHz (consumer), 1,5 GHz (Industrial)
Cortex[®]-M33 @250 MHz
Ethos U-65 microNPU

Memory

Up to 2 GByte of 16-bit LPDDR4

Video Interfaces

1x LVDS Single Channel
1x MIPI or eDP interface

Video Resolution

LVDS, resolution up to 720p @ 60Hz
MIPI or eDP resolution up to 1080p @60Hz

Mass Storage

SD 4-bit interface boot device

Networking

2x Gigabit Ethernet interface
WiFi 802.11a/b/g/n/ac
BT 5.0

USB

1x USB 2.0 OTG port
Up to 4 x USB 2.0 port (by internal Hub)

Audio

1x I2S Audio interface

Serial ports

2x UART Tx/Rx/RTS/CTS

2x UART Tx/Rx
2x CAN Bus

Other Interfaces

1x 2-lanes MIPI_CSI camera interfaces
3x I2C Interfaces
SPI interface
12x GPIOs
2x PWM

Features

TPM

Power supply voltage: +5V_{DC}

RTC voltage: 3.3V

Operating temperature:

Commercial version 0°C ÷ +60°C **
Industrial version -40°C ÷ +85°C **.

Dimensions: 50 x82 mm (1.97" x 3.23")

Supported Operating Systems:

Linux 64-bit



*** Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated. Please also check paragraph 4.2*

2.3 Electrical Specifications

According to SMARC specifications, the SOM-SMARC-MX93 module needs to be supplied only with an external +5V_{DC} power supply.

For Real Time Clock working it is also needed a backup battery voltage. All these voltages are supplied directly through card edge fingers (see connector's pinout).

All remaining voltages needed for board's working are generated internally from +5V_{DC} power rail.

2.3.1 Power Consumption

SOM-SMARC-MX93 module, like all SMARC modules, needs a carrier board for its normal working. All connections with the external world come through this carrier board, which also provides the required voltage to the board.

Measurements of power consumption from VDD_IN power rail (5V_{DC}) that supplies the board are reported here for 3 different board factory configurations.

Status	Processor
	i.MX 93 2GB LPDDR4 32GB eMMC
Video	eDP
Power requirement	5V
Idle mode power consumption	850 mW
Power consumption max.	13.16W
RTC Power consumption on VDD_RTC (when VDD_IN off)	300nA

Please consider that power consumption is strongly dependent on the board's configuration, on number of processor cores active and from the interfaces that are SW enabled.

2.3.2 Power Rails meanings

In all the tables contained in this manual, Power rails are named with the following meaning:

VDD_IN: Module power input voltage. +5V voltage directly coming from the card edge connector.

VDD_RTC: Low current RTC circuit backup power. 3V coin cell voltage coming from the edge card for supplying the RTC clock on the I.MX 8M

_RUN: Switched voltages, i.e. power rails that are active only when the board is in ACPI's S0 (Working) state. Examples: +1.8V_RUN, +3.3V_RUN, +5V_RUN.

_ALW: Always-on voltages, i.e. power rails that are active both in ACPI's S0 (Working), S3 (Standby) and S5 (Soft Off) state. Examples: +5V_ALW, +3.3V_ALW.

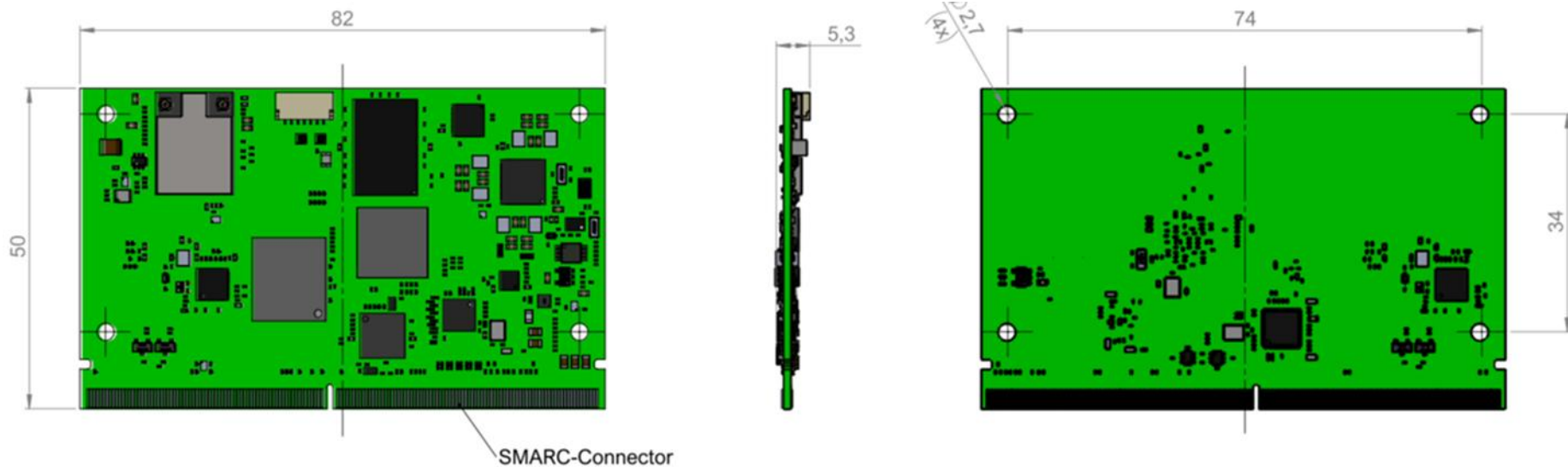
2.4 Mechanical Specifications

According to SMARC® specifications, the board dimensions are: 50 x 82 mm (1.97" x 3.23") including the pin numbering and edge finger pattern.

Printed circuit of the board is made of ten layers, some of them are ground planes, for disturbance rejection.

The MXM connector accommodates various connector heights for different carrier board applications needs.

When using different connector heights, please consider that, according to SMARC specifications, components placed on bottom side of the module will have a maximum height of 1.3mm. Keep this value in mind when choosing the MXM connector's height, if there is the need to place components on the carrier board in the zone below the SMARC module.



2.5 Supported Operating Systems

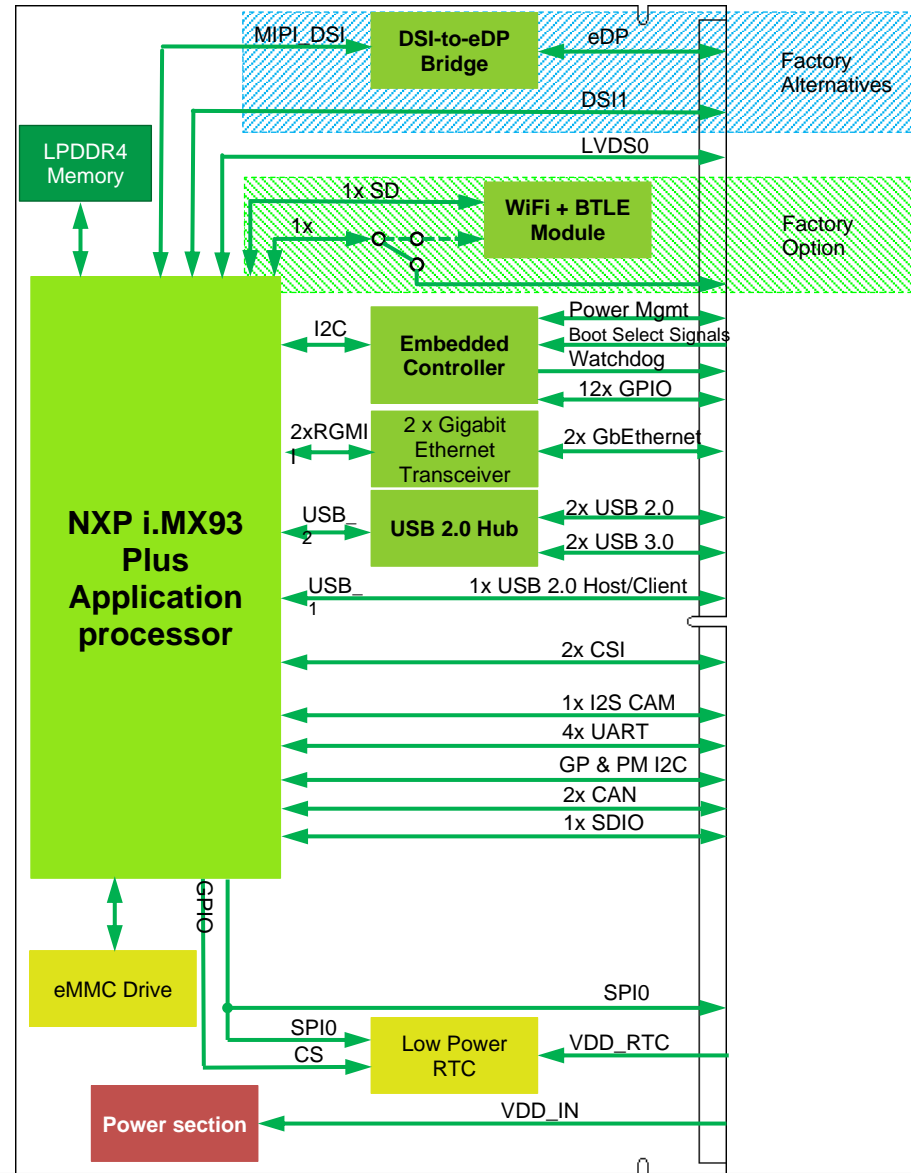
SOM-SMARC-MX93 module supports the following operating systems:

- Linux

SECO will offer the BSP (Board Support Package) for these OS, to reduce at minimum SW development of the board, supplying all the drivers and libraries needed for use both with the SMARC board and the Carrier Board, assuming that the Carrier Board is designed following SECO SMARC Design Guide, with the same IC's.

For further details, please visit <https://www.seco.com>.

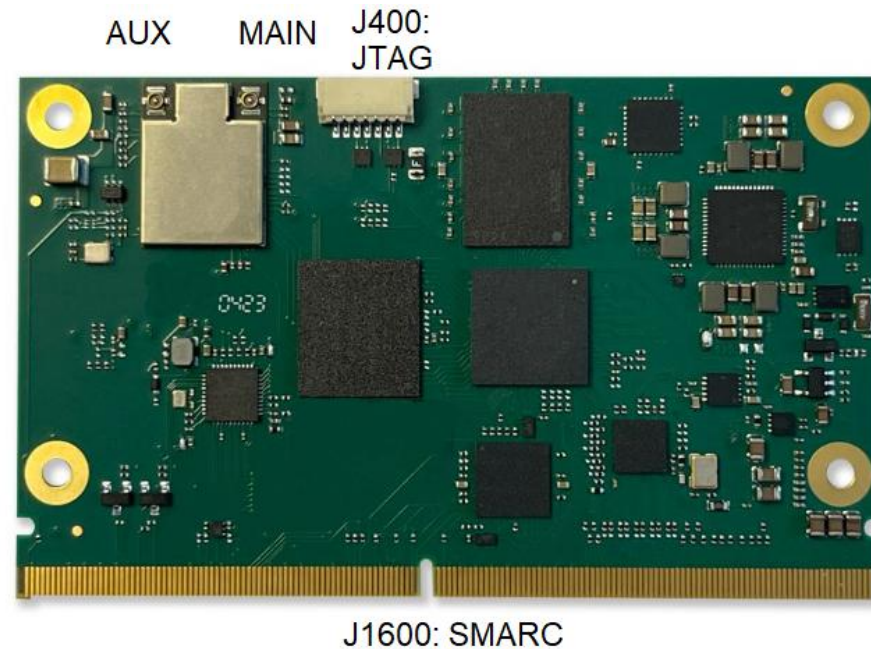
2.6 Block Diagram



Chapter 3.

CONNECTORS

- Introduction
- Connectors description



3.1 Introduction

According to SMARC specifications, all interfaces to the board are available through a single card edge connector.

TOP SIDE

BOTTOM SIDE



Card edge golden
finger, pin P1

Card edge golden
finger, pin P156

Card edge golden
finger, pin S158

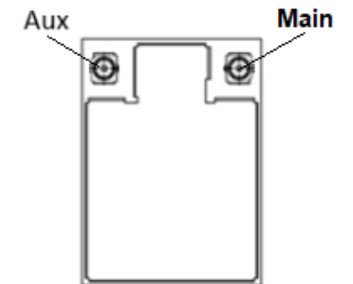
Card edge golden
finger, pin S1

3.2 Connectors description

3.2.1 WiFi/BTLE Module

This SMARC® module can be equipped, by factory option, with a Dual band (2.4GHz + 5.0 GHz) WLAN 802.11 a/b/g/n/ac + BT 5.0 combo embedded module AzureWave p/n AW-CM276NF.

Aux antenna is used for WLAN and BT while main antenna is used for WLAN only. These are type IPEX MHF4 RF connectors.



3.2.2 SMARC® Connector

According to SMARC® Rel 2.1 specification, all interface signals are reported on the card edge connector, which is a 314-pin Card Edge that can be inserted into standard low profile 314 pin 0.5mm right pitch angle connector that was originally defined for use with MXM3 graphics cards.

Not all signals contemplated in the SMARC® Rel 2.1 are implemented on card edge connector, therefore, please refer to the following table for a list of effective signals reported on the card edge connector.

Consider that the signals labelled as RSVD are for factory production use only and shall be left unused, otherwise the module may not boot or function properly.

For accurate signals description, please consult the following paragraphs.

SMARC® Golden Finger Connector – CN2							
TOP SIDE				BOTTOM SIDE			
SIGNAL GROUP	Type	Pin name	Pin nr.	Pin nr.	Pin name	Type	SIGNAL GROUP
				S1	N.C.		
MANAGEMENT	I	SMB_ALERT_IV8#	P1	S2	N.C.		
		GND	P2	S3	GND		
		N.C.	P3	S4	RSVD		
		N.C.	P4	S5	I2C1_SCL	O	I2C
		N.C.	P5	S6	CAM_MCK	O	CAMERA
		N.C.	P6	S7	I2C1_SDA	I/O	I2C
		N.C.	P7	S8	CSIO_CK+	I	CAMERA
		N.C.	P8	S9	CSIO_CK-	I	CAMERA
		GND	P9	S10	GND		
		N.C.	P10	S11	CSIO_RX0+	I	CAMERA
		N.C.	P11	S12	CSIO_RX0-	I	CAMERA
		GND	P12	S13	GND		
		N.C.	P13	S14	CSIO_RX1+	I	CAMERA
		N.C.	P14	S15	CSIO_RX1-	I	CAMERA
		GND	P15	S16	GND		

		N.C.	P16	S17	GBE1_MDIO+	I/O	GBE
		N.C.	P17	S18	GBE1_MDIO-	I/O	GBE
		GND	P18	S19	GBE1_LINK100#	O	GBE
GBE	I/O	GBE0_MDIO-	P19	S20	GBE1_MDIO+	I/O	GBE
GBE	I/O	GBE0_MDIO+	P20	S21	GBE1_MDIO-	I/O	GBE
GBE	O	GBE0_LINK100#	P21	S22	GBE1_LINK1000#	O	GBE
GBE	O	GBE0_LINK1000#	P22	S23	GBE1_MDIO2+	I/O	GBE
GBE	I/O	GBE0_MDIO-	P23	S24	GBE1_MDIO-	I/O	GBE
GBE	I/O	GBE0_MDIO+	P24	S25	GND		
GBE	O	GBE0_LINK_ACT#	P25	S26	GBE1_MDIO3+	I/O	GBE
GBE	I/O	GBE0_MDIO-	P26	S27	GBE1_MDIO-	I/O	GBE
GBE	I/O	GBE0_MDIO+	P27	S28	N.C.		
		N.C.	P28	S29	N.C.		
GBE	I/O	GBE0_MDIO-	P29	S30	N.C.		
GBE	I/O	GBE0_MDIO+	P30	S31	GBE1_LINK_ACT#	O	GBE
		N.C.	P31	S32	N.C.		
		GND	P32	S33	N.C.		
		N.C.	P33	S34	GND		
SDIO_CARD	I/O	SDIO_CMD	P34	S35	USB4+	I/O	USB
SDIO_CARD	I	SDIO_CD#	P35	S36	USB4-	I/O	USB
SDIO_CARD	O	SDIO_CK	P36	S37	N.C.		
SDIO_CARD	O	SDIO_PWR_EN	P37	S38	I2S0_MCK	O	AUDIO
		GND	P38	S39	I2S0_LRCK	I/O	AUDIO
SDIO_CARD	I/O	SDIO_D0	P39	S40	I2S0_SDOUT	O	AUDIO
SDIO_CARD	I/O	SDIO_D1	P40	S41	I2S0_SDIN	I	AUDIO
SDIO_CARD	I/O	SDIO_D2	P41	S42	I2S0_CK	O	AUDIO
SDIO_CARD	I/O	SDIO_D3	P42	S43	N.C.		
SPI_INTERFACE	O	SPI_CS0#	P43	S44	N.C.		
SPI_INTERFACE	O	SPI_CK	P44	S45	N.C.		

SPI_INTERFACE	I	SPIO_DIN	P45	S46	N.C.		
SPI_INTERFACE	O	SPIO_DO	P46	S47	GND		
		GND	P47	S48	I2C3_SCL	I/O	I2C
		N.C.	P48	S49	I2C3_SDA	I/O	I2C
		N.C.	P49	S50	I2S2_LRCK	I/O	AUDIO
		GND	P50	S51	I2S2_SDOOUT	O	AUDIO
		N.C.	P51	S52	I2S2_SDIN	I	AUDIO
		N.C.	P52	S53	I2S2_CK	O	AUDIO
		GND	P53	S54	N.C.		
		N.C.	P54	S55	N.C.		
		N.C.	P55	S56	N.C.		
		N.C.	P56	S57	N.C.		
		N.C.	P57	S58	N.C.		
		N.C.	P58	S59	N.C.		
		GND	P59	S60	N.C.		
USB	I/O	USB0+	P60	S61	GND		
USB	I/O	USB0-	P61	S62	N.C.		
USB	I/O	USB0_EN_OC#	P62	S63	N.C.		
USB	I	USB0_VBUS_DET	P63	S64	GND		
USB	I	USB0_OTG_ID	P64	S65	N.C.		
USB	I/O	USB1+	P65	S66	N.C.		
USB	I/O	USB1-	P66	S67	GND		
USB	I/O	USB1_EN_OC#	P67	S68	USB3+	I/O	USB
		GND	P68	S69	USB3-	I/O	USB
USB	I/O	USB2+	P69	S70	GND		
USB	I/O	USB2-	P70	S71	N.C.		
USB	I/O	USB2_EN_OC#	P71	S72	N.C.		
STM32		STM32_RST	P72	S73	GND		
		N.C.	P73	S74	N.C.		

USB	I/O	USB3_EN_OC#	P74	S75	N.C.
		N.C.	P75	S76	N.C.
USB	I/O	USB4_EN_OC#	P76	S77	N.C.
PCI_e	I/O	PCIE_B_CKREQ#	P77	S78	N.C.
PCI_e	I/O	PCIE_A_CKREQ#	P78	S79	N.C.
		GND	P79	S80	GND
		N.C.	P80	S81	N.C.
		N.C.	P81	S82	N.C.
		GND	P82	S83	GND
		N.C.	P83	S84	N.C.
		N.C.	P84	S85	N.C.
		GND	P85	S86	GND
		N.C.	P86	S87	N.C.
		N.C.	P87	S88	N.C.
		GND	P88	S89	GND
		N.C.	P89	S90	N.C.I
		N.C.	P90	S91	N.C.
		GND	P91	S92	GND
		N.C.	P92	S93	N.C.
		N.C.	P93	S94	N.C.
		GND	P94	S95	DPO_AUX_SEL
		N.C.	P95	S96	N.C.
		N.C.	P96	S97	N.C.
		GND	P97	S98	DPO_HPD
		N.C.	P98	S99	N.C.
		N.C.	P99	SI00	N.C.
		GND	PI00	SI01	GND
		N.C.	PI01	SI02	N.C.
		N.C.	PI02	SI03	N.C.

		GND	P103	S104	N.C.		
SECONDARY_DISPLAY	I	HDMI_HPD	P104	S105	DPO_AUX+		1M Pulldown
SECONDARY_DISPLAY	I/O	HDMI_CTRL_CK	P105	S106	DPO_AUX-		100K Pullup
SECONDARY_DISPLAY	I/O	HDMI_CTRL_DAT	P106	S107	LCD1_BKLT_EN	O	LCD_SUPPORT
	I	DPI_AUX_SEL	P107	S108	EDP_DSI_CLK+	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO0 / CAM0_PWR#	P108	S109	EDP_DSI_CLK-	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO1 / CAM1_PWR#	P109	S110	GND		
GPIO	I/O	GPIO2 / CAM0_RST#	P110	S111	EDP_DSI_D0+	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO3 / CAM1_RST#	P111	S112	EDP_DSI_D0-	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO4	P112	S113	EDPI_HPD	I	PRIMARY_DISPLAY
GPIO	I/O	GPIO5	P113	S114	EDP_DSI_D1+	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO6	P114	S115	EDP_DSI_D1-	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO7	P115	S116	LCD1_VDD_EN	O	LCD_SUPPORT
GPIO	I/O	GPIO8	P116	S117	EDP_DSI_D2+	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO9	P117	S118	EDP_DSI_D2-	O	PRIMARY_DISPLAY
GPIO	I/O	GPIO10	P118	S119	GND		
GPIO	I/O	GPIO11	P119	S120	EDP_DSI_D3+	O	PRIMARY_DISPLAY
		GND	P120	S121	EDP_DSI_D3-	O	PRIMARY_DISPLAY
MANAGEMENT	I/O	I2C_PM_CK	P121	S122	LCD1_BKLT_PWM	O	LCD_SUPPORT
MANAGEMENT	I/O	I2C_PM_DAT	P122	S123	GPIO13	I/O	GPIO
BOOT_SEL	I	BOOT_SELO#	P123	S124	GND		
BOOT_SEL	I	BOOT_SEL1#	P124	S125	LVDS0_0+	O	PRIMARY_DISPLAY
BOOT_SEL	I	BOOT_SEL2#	P125	S126	LVDS0_0-	O	PRIMARY_DISPLAY
MANAGEMENT	O	RESET_OUT#	P126	S127	LCD0_BKLT_EN	O	LCD_SUPPORT
MANAGEMENT	I	RESET_IN#	P127	S128	LVDS0_1+	O	PRIMARY_DISPLAY
MANAGEMENT	I	POWER_BTN#	P128	S129	LVDS0_1-	O	PRIMARY_DISPLAY
ASYNC_SERIAL	O	SER0_TX	P129	S130	GND		
ASYNC_SERIAL	I	SER0_RX	P130	S131	LVDS0_2+	O	PRIMARY_DISPLAY
ASYNC_SERIAL	O	SER0_RTS#	P131	S132	LVDS0_2-	O	PRIMARY_DISPLAY

ASYNC_SERIAL	I	SER0_CTS#	P132	SI33	LCD0_VDD_EN	O	LCD_SUPPORT
		GND	P133	SI34	LVDS0_CK+	O	PRIMARY_DISPLAY
ASYNC_SERIAL	O	SER1_TX	P134	SI35	LVDS0_CK-	O	PRIMARY_DISPLAY
ASYNC_SERIAL	I	SER1_RX	P135	SI36	GND		
ASYNC_SERIAL	O	SER2_TX	P136	SI37	LVDS0_3+	O	PRIMARY_DISPLAY
ASYNC_SERIAL	I	SER2_RX	P137	SI38	LVDS0_3-	O	PRIMARY_DISPLAY
ASYNC_SERIAL	O	SER2_RTS#	P138	SI39	I2C1_SCL	O	LCD_SUPPORT
ASYNC_SERIAL	I	SER2_CTS#	P139	SI40	I2C1_SDA	I/O	LCD_SUPPORT
ASYNC_SERIAL	O	SER3_TX	P140	SI41	LCD0_BKLT_PWM	O	LCD_SUPPORT
ASYNC_SERIAL	I	SER3_RX	P141	SI42	GPIO12	I/O	GPIO
		GND	P142	SI43	GND		
CAN	O	CAN0_TX	P143	SI44	eDPO_HP	I	PRIMARY_DISPLAY
CAN	I	CAN0_RX	P144	SI45	WDT_TIME_OUT#	O	WATCHDOG
CAN	O	CAN1_TX	P145	SI46	N.C.		
CAN	I	CAN1_RX	P146	SI47	VDD_RTC		
5V_SLEEP		VDD_IN	P147	SI48	LID#	I	MANAGEMENT
5V_SLEEP		VDD_IN	P148	SI49	SLEEP#	I	MANAGEMENT
5V_SLEEP		VDD_IN	P149	SI50	VIN_PWR_BAD#	I	MANAGEMENT
5V_SLEEP		VDD_IN	P150	SI51	CHARGING#	I	MANAGEMENT
5V_SLEEP		VDD_IN	P151	SI52	CHARGER_PRSENT#	I	MANAGEMENT
5V_SLEEP		VDD_IN	P152	SI53	CARRIER_STBY#	O	MANAGEMENT
5V_SLEEP		VDD_IN	P153	SI54	CARRIER_PWR_ON	O	MANAGEMENT
5V_SLEEP		VDD_IN	P154	SI55	FORCE_RECOV#	I	BOOT_SEL
5V_SLEEP		VDD_IN	P155	SI56	BATLOW#	I	MANAGEMENT
5V_SLEEP		VDD_IN	P156	SI57	TEST#	I	MANAGEMENT
				SI58	GND		



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3.2.2.1 LCD Display Support Signals

The panel control signals are:

LCDO_VDD_EN: Panel #0 VDD enable signal. Set high to enable. +1.8V_RUN electrical level Output.

LCDO_BKLT_EN: Panel #0 Backlight Enable signal. It can be used to turn On/Off the backlight's lamps of a connected LVDS display. +1.8V_RUN electrical level Output

LCDO_BKLT_PWM: This signal can be used to adjust the Panel #0 backlight brightness in displays supporting Pulse Width Modulated (PWM) regulations. +1.8V_RUN electrical level Output

LCDI_VDD_EN: Panel #1 VDD enable signal. Set high to enable. +1.8V_RUN electrical level Output

LCDI_BKLT_EN: Panel #1 Backlight Enable signal. It can be used to turn On/Off the backlight's lamps of a connected LVDS display. +1.8V_RUN electrical level Output.

LCDI_BKLT_PWM: This signal can be used to adjust the Panel #1 backlight brightness in displays supporting Pulse Width Modulated (PWM) regulations. +1.8V_RUN electrical level Output.

I2C LCD signals are managed by SoC I2C1 bus.

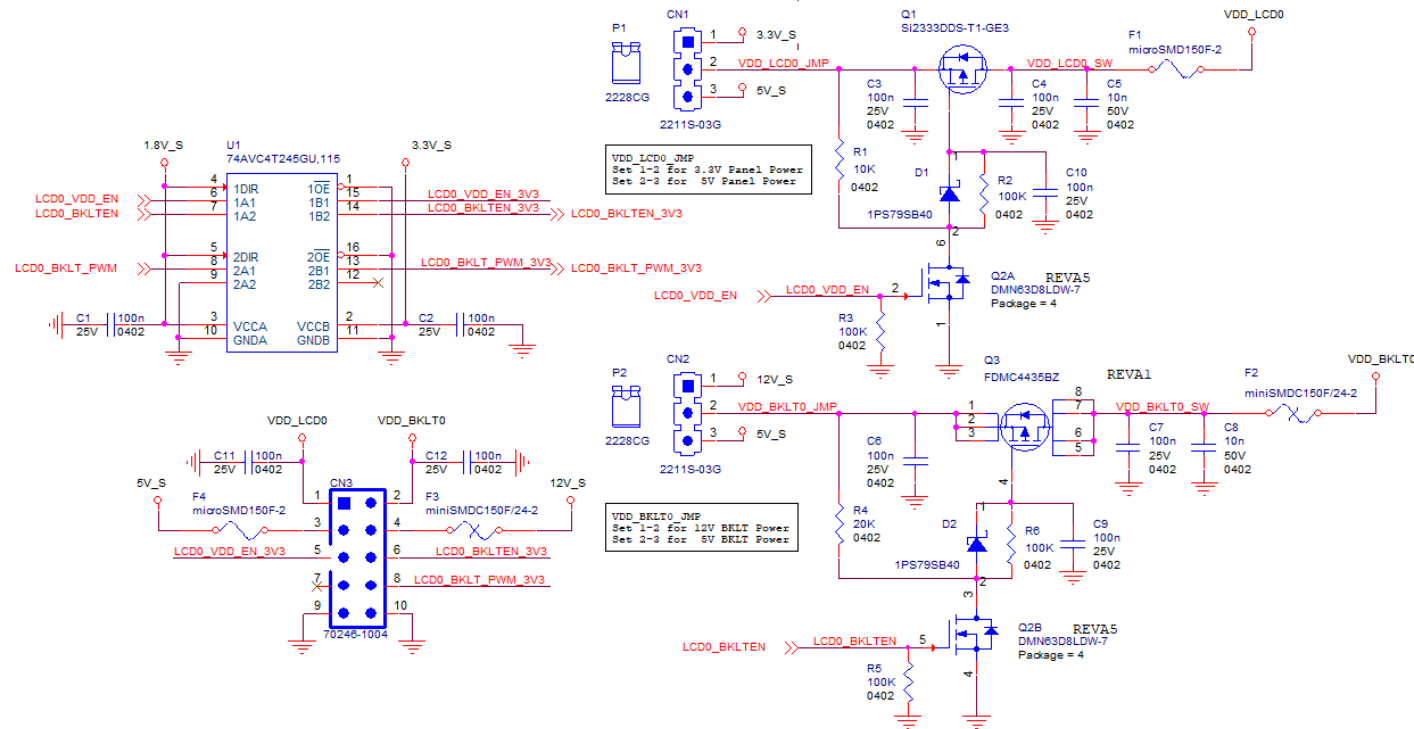
I2C1_SCL: LCD I2C Data. This signal is used to read the LCD display EDID EEPROM. +1.8V_RUN electrical level Bidirectional with a 2k2Ω pull-up resistor.

I2C1_SDA: LCD I2C Clock. This signal is used to read the LCD display EDID EEPROM. +1.8V_RUN electrical level Output with a 2k2Ω pull-up resistor.

On this bus a selection of addresses must be left reserved for on-board peripherals as presented in this table (also consider that this bus is shared with CAM0 from par. 3.2.2.3):

I2C2 Bus	
Address	Peripheral
0x2D	DSI Bridge

Please refer to the following schematics as an example of connection of LCD display control signals and supply voltage selection jumpers.



3.2.2.2 MIPI-DSI / eDP (factory alternatives) and LVDS Single Channel

A LVDS interface with 4-lanes and a maximum supported resolution of max. 720p @ 60Hz, is natively supported by the SOC additional there is a MIPI-DSI / eDP interface with a resolution up to 1080p@60Hz.

EITHER the signals for Channel #0 are MIPI_DSI:

DSII_D0+/DSII_D0-: MIPI-DSI Channel #0 differential data pair #0.

DSII_D1+/DSII_D1-: MIPI-DSI Channel #0 differential data pair #1.

DSII_D2+/DSII_D2-: MIPI-DSI Channel #0 differential data pair #2.

DSII_D3+/DSII_D3-: MIPI-DSI Channel #0 differential data pair #3.

DSII_CLK+/ DSII_CLK-: MIPI-DSI Channel #0 differential Clock.

OR the signals for Channel #0 are eDP:

eDPO_TX0+/ eDPO_TX0-: eDP Channel #0 differential data pair #0.

eDPO_TX1+/ eDPO_TX1-: eDP Channel #0 differential data pair #1.

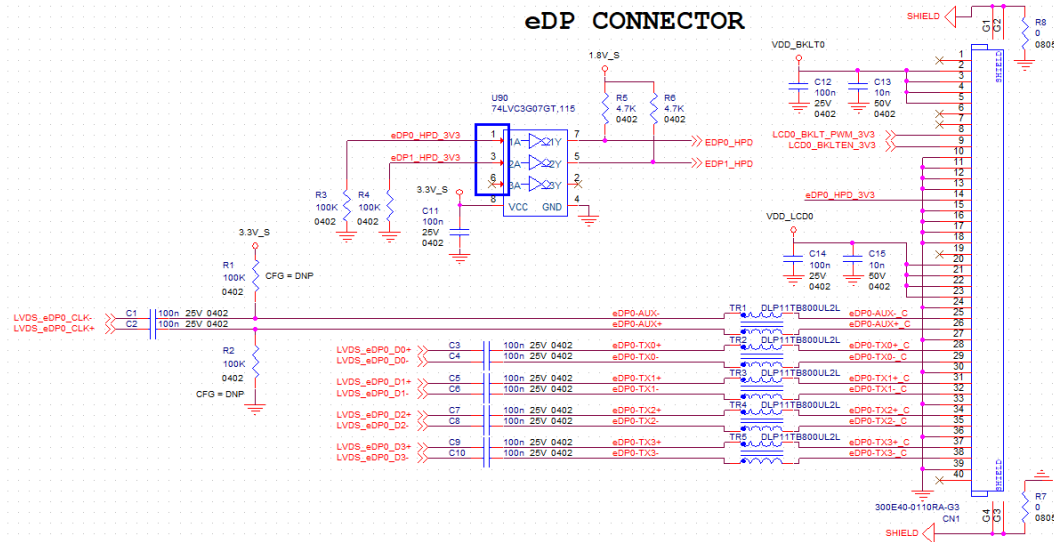
eDPO_TX2+/ eDPO_TX2-: eDP Channel #0 differential data pair #2.

eDPO_TX3+/ eDPO_TX3-: eDP Channel #0 differential data pair #3.

eDPO_AUX+/ eDPO_AUX-: eDP Channel #0 differential Clock.

eDPO_HPD: Hot Plug Detect, Active high Input signal of +1.8V_RUN electrical level from carrier board. 1M Ω pull-down resistor is placed on module for this signal.

Please refer to the following schematics as an example of connection of eDP interface on the carrier board. Hot Plug Detect signal must be buffered to prevent back feeding of power from the display to the module as well as level translation.

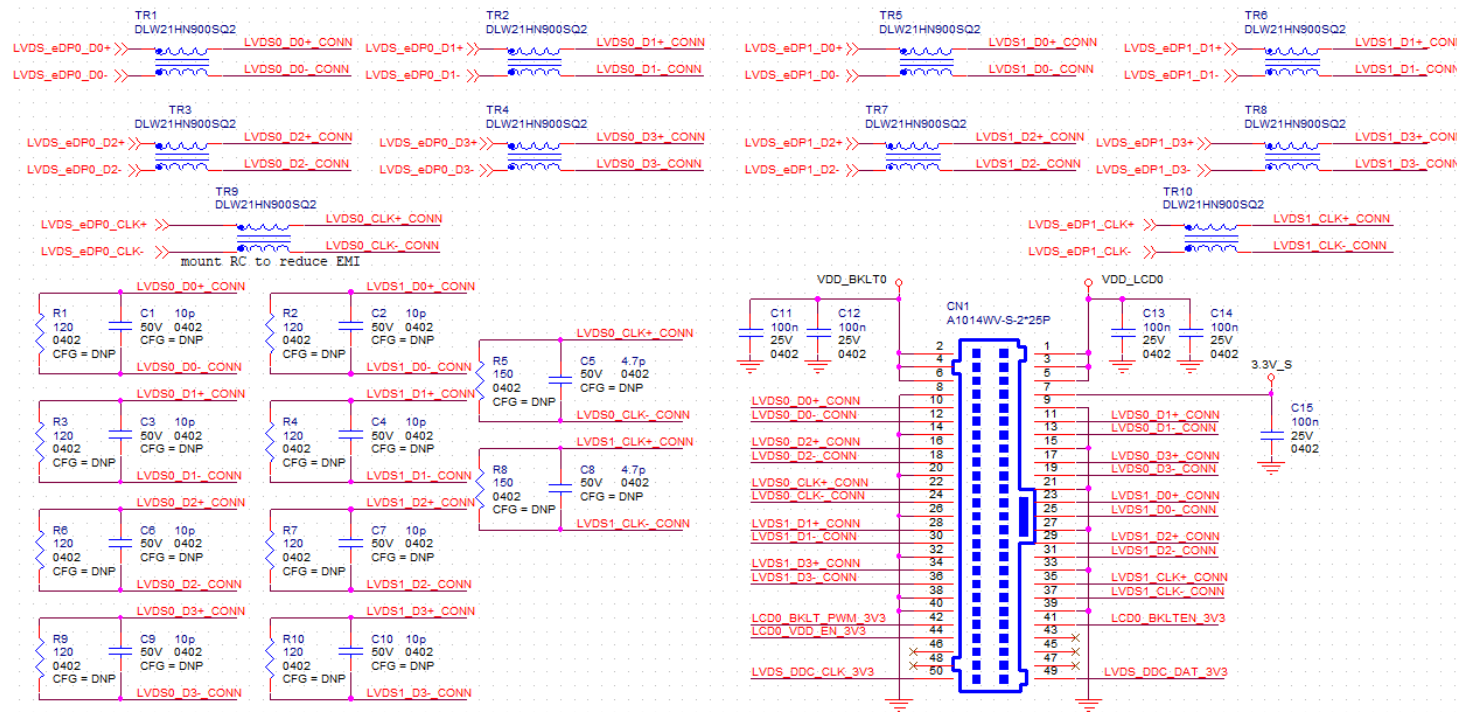


The signals for Channel #1 of the LVDS interface is always available on the edge pinout regardless of the factory board configuration.

- LVDSI_1+ / LVDSI_0- : LVDS Channel #1 differential data pair #0
- LVDSI_1+ / LVDSI_1-: LVDS Channel #1 differential data pair #1
- LVDSI_2+ / LVDSI_2-: LVDS Channel #1 differential data pair #2
- LVDSI_3+ / LVDSI_3-: LVDS Channel #1 differential data pair #3
- LVDSI_CK+ / LVDSI_CK-: LVDS Channel #1 differential Clock

Please refer to the following schematics as an example of connection of dual channel LVDS interface on the carrier board, with EMI filtering section included.

LVDS CONNECTORS



3.2.2.3 Serial Camera

There is one MIPI-CSI2 interfaces available. The CSI0 interface supports two lanes. Consider that from the SoC the CSI0 interface is managed by the MIPI_CSI0 group signals and I2C2 bus, while CSI1 is managed by MIPI.

CSI0_CK+/CSI0_CK-: 2-lane CSI Input Clock Differential Pair

CSI0_RX0+/CSI0_RX0-: 2-lane CSI Input Differential Pair 0

CSI0_RX1+/CSI0_RX1-: 2-lane CSI Input Differential Pair 1

GPIO0/CAM0_PWR#: Camera 0 power enable signal (active low)

GPIO1/CAM1_PWR#: Camera 1 power enable signal (active low)

GPIO2/CAM0_RST#: Camera 0 reset signal (active low)

GPIO3/CAM1_RST#: Camera 1 reset signal (active low)

On this bus a selection of addresses must be left reserved for on-board peripherals as presented in this table (also consider that this bus is shared with LCD signals from par. 3.2.2.1):

I2C2 Bus	
Address	Peripheral
0x2D	DSI Bridge
0x48	Secure Element

I2C_CAM1_CK: CSI Port #1 dedicated I2C Bus Clock signal, Bi-Directional, electrical level +1.8V_RUN with a 2k2Ω pull-up resistor.

I2C_CAM1_DAT: CSI Port #1 dedicated I2C Bus Data signal, Bi-Directional, electrical level +1.8V_RUN with a 2k2Ω pull-up resistor.

On this bus a selection of addresses must be left reserved for on-board peripherals as presented in this table:

I2C3 Bus	
Address	Peripheral
0x68	RTC
0x20	EEPROM

3.2.2.4 SDIO interface signals

The NXP i.MX 93 processors offer many different SDIO interfaces, that can be used independently one from the other to implement different mass storages (internal eMMC, internal SD Card, external SDIO interface).

The SDIO1 signals of the processor are used for the onboard eMMC storage of the module.

The SDIO3 signals of the processor are used for the factory optional onboard WiFi/BTLE module.

The SDIO2 interface of the processor is externally accessible through the edge connector of the module. Supporting 4-bit mode as per the SMARC specification.

The uSDHC controller complies with:

- SD Host Controller Standard Specification version 3.0 with SDR104 signaling to support up to 104MB/sec.
- MMC System Specification version 5.0

The edge accessible SDIO2 signals are as follows:

SDIO_CMD: Command/Response line. Used to send command from Host (i.MX 8M processor) to the connected card, and to send the response from the card to the Host.

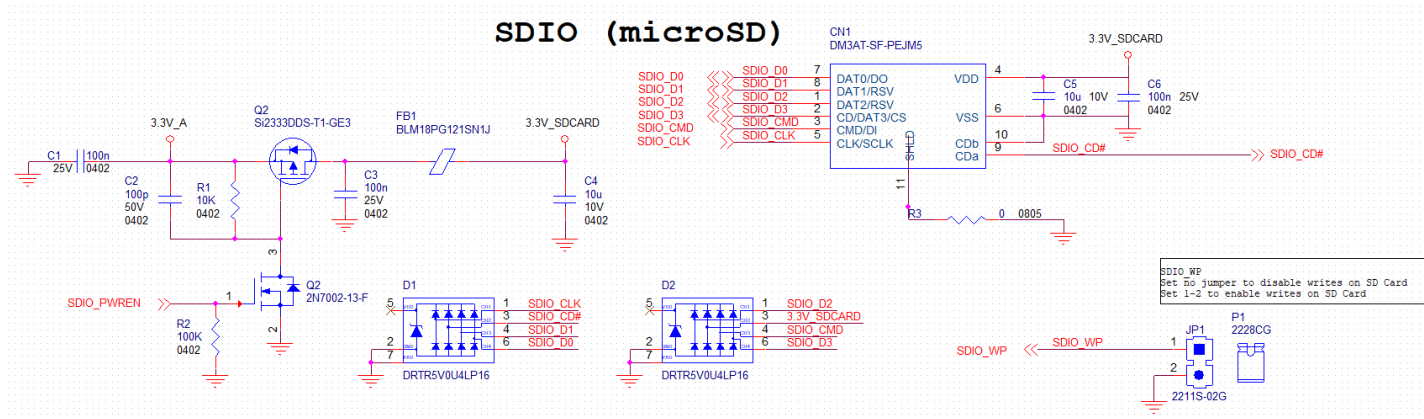
SDIO_CD#: Card Detect Input. Active Low Signal, electrical level +1.8V_RUN (SDR104) or +3.3V_RUN with 10kΩ pull-up resistor. This signal must be externally pulled low to signal that a SDIO/MMC Card is present.

SDIO_CK: Clock Line (output), up to 200MHz maximum frequency for SDR104 Mode (4-bit only).

SDIO_PWR_EN: SDIO Power Enable output, active high signal, electrical level +1.8V_RUN (SDR104) or +3.3V_RUN with 2.2kΩ pull-up resistor. It is used to enable the power line supplying SD/SDIO/MMC devices.

SDIO_[D0÷D3]: SDIO data bus. Signals for 4-bit SD/SDIO/MMC communication mode.

Please refer to the following schematics as an example of connection of SDIO interface on the carrier board, with Voltage clamping diodes highly recommended on all signal lines for ESD suppression.



3.2.2.5 SPI interface signals

The signals related to SPI0 are as follows:

SPI0_CS0#: SPI primary Chip select, active low output signal. Electrical level +1.8V_RUN

SPI0_CK: SPI Clock Output to carrier board's SPI embedded devices. Electrical level +1.8V_RUN

SPI0_DIN: SPI0 Master Data Input, electrical level +1.8V_RUN. Input to i.MX 8M from SPI devices embedded on the Carrier Board.

SPI0_DO: SPI0 Master Data Output, electrical level +1.8V_RUN. Output from i.MX 8M to SPI devices embedded on the Carrier Board

SPI interface can support speed up to 20MHz.

3.2.2.6 Audio interface signals

Here are following the signals related to I2S Audio interfaces:

The first I2S interface managed by the SAI2 group of signals of the SoC is always available on the edge pinout:

I2S0_MCLK: Master clock output to Audio codec. Output from the module to the Carrier board, electrical level +1.8V_RUN

I2S0_LRCK: Left& Right audio synchronization clock. Bi-Directional between the module to the Carrier board, electrical level +1.8V_RUN

I2S0_SDOUT: Digital audio Output. Output from the module to the Carrier board, electrical level +1.8V_RUN

I2S0_SDIN: Digital audio Input. Input from the module to the Carrier board, electrical level +1.8V_RUN

I2S0_CK: Digital audio clock. Bi-Directional between the module to the Carrier board, electrical level +1.8V_RUN

A second I2S interface is routed between SMARC connector and the to the Wi-Fi module to support BT-Audio.

I2S2_LRCK: Left& Right audio synchronization clock. Bi-Directional between the module to the Carrier board, electrical level +1.8V_RUN

I2S2_SDOUT: Digital audio Output. Output from the module to the Carrier board, electrical level +1.8V_RUN

I2S2_SDIN: Digital audio Input. Input from the module to the Carrier board, electrical level +1.8V_RUN

I2S2_CK: Digital audio clock. Bi-Directional between the module to the Carrier board, electrical level +1.8V_RUN

Signals routed to the Carrier Board have to be connected to I2S Audio Codecs. Please refer to the chosen Codec's Reference Design Guide for correct implementation of audio section on the carrier board.

3.2.2.7 I2C Interface

I2C General Purpose signals are managed by SoC I2C5 bus.

I2C_GP_CK: I2C General Purpose clock signal. Bi-Directional between the module to the Carrier board, electrical level +1.8V_RUN with a 2k2Ω pull-up resistor

I2C_GP_DAT: I2C General Purpose data signal. Bi-Directional between the module to the Carrier board, electrical level +1.8V_RUN with a 2k2Ω pull-up resistor

On this bus a selection of addresses must be left reserved for on-board peripherals as presented in this table:

I2C3 Bus	
Address	Peripheral
0x50	EEPROM

I2C Power Management signals are managed by SoC I2C1 bus.

I2C_PM_CK: Power management clock signal. Bi-Directional between the module to the Carrier board, electrical level +1.8V_ALW with 2.2kΩ pull-up resistor.

I2C_PM_DAT: Power management data signal. Bi-Directional between the module to the Carrier board, electrical level +1.8V_ALW with 2.2kΩ pull-up resistor

On this bus a selection of addresses must be left reserved for on-board peripherals as presented in this table:

I2C_PM	
Address	Peripheral
0x40	Embedded Controller
0x25	PMIC

3.2.2.8 Asynchronous Serial Ports (UART) interface signals

All UART interface signals are directly managed by the i.MX 93 processor. In all versions, the edge connector offers the four following UART interfaces.

SER0_TX: UART #2 Interface, Serial data Transmit (output) line, +1.8V_RUN electrical level

SER0_RX: UART #2 Interface, Serial data Receive (input) line, +1.8V_RUN electrical level with a 100kΩ pull-up resistor

SER0_RTS#: UART #2 Interface, Handshake signal, Request to Send (output) line, +1.8V_RUN electrical level

SER0_CTS#: UART #2 Interface, Handshake signal, Clear to Send (Input) line, +1.8V_RUN electrical level with a 100kΩ pull-up resistor

SER1_TX: UART #4 Interface, Serial data Transmit (output) line, +1.8V_RUN electrical level

SER1_RX: UART #4 Interface, Serial data Receive (input) line, +1.8V_RUN electrical level with a 100kΩ pull-up resistor

SER2_TX: UART #3 Interface, Serial data Transmit (output) line, +1.8V_RUN electrical level

SER2_RX: UART #3 Interface, Serial data Receive (input) line, +1.8V_RUN electrical level with a 100kΩ pull-up resistor

SER2_RTS#: UART #3 Interface, Handshake signal, Request to Send (output) line, +1.8V_RUN electrical level

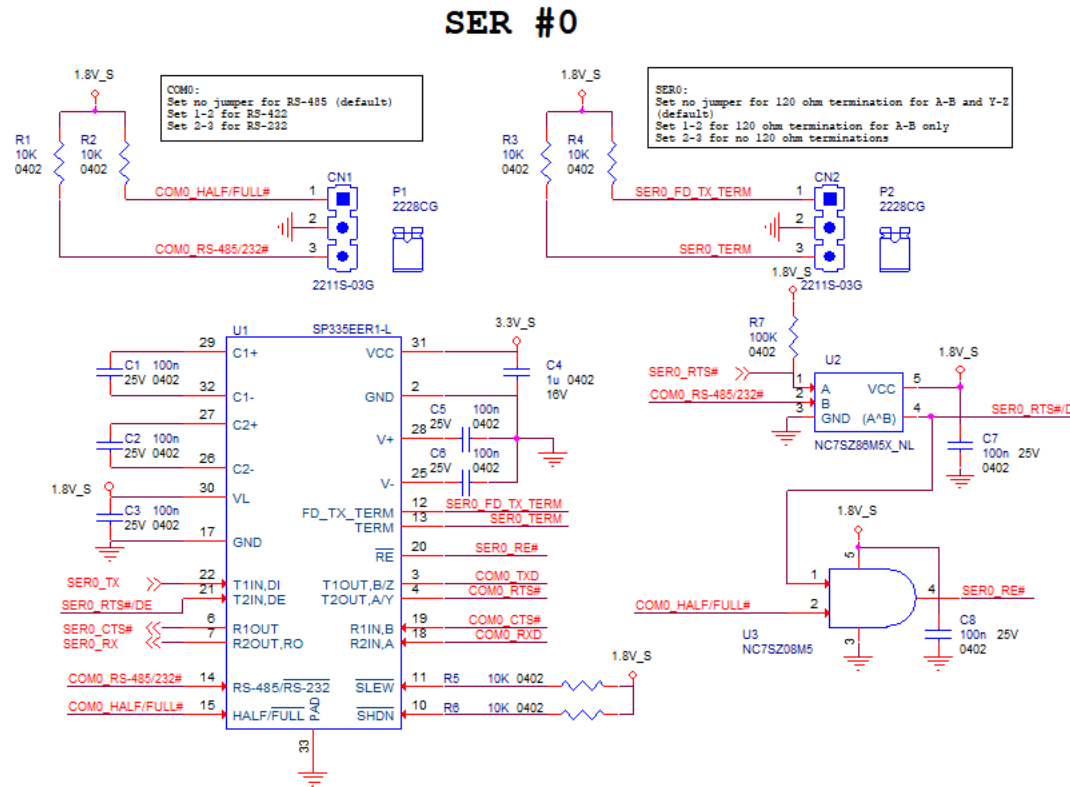
SER2_CTS#: UART #3 Interface, Handshake signal, Clear to Send (Input) line, +1.8V_RUN electrical level with a 100kΩ pull-up resistor.

SER3_RX: UART #1 Interface, Serial data Receive (input) line, +1.8V_RUN electrical level with a 100kΩ pull-up resistor

SER3_TX: UART #1 Interface, Serial data Transmit (output) line, +1.8V_RUN electrical level

Please consider that interface is at +1.8V_RUN electrical level; therefore, please evaluate well the typical scenario of application. If there isn't any explicit need of interfacing directly at +1.8V_RUN level, for connection to standard serial ports commonly available (like those offered by common PCs, for example) it is mandatory to include an RS-232 transceiver on the carrier board.

In the following schematic here is an example of UART interface on the carrier board, with a multiprotocol transceiver allowing to support RS485/RS-422/RS-232 serial interfaces.



3.2.2.9 USB interface signals

The module has up to 4x USB ports consisting of 1x USB 2.0 port from the NXP i.MX 93 processor USB 2.0 controller which can be configured at kernel compile time to work as Host or Client, the additional 4x USB 2.0 were using the optional USB 2.0 hub controller.

Here following the signals related to USB interfaces.

USB0+/ USB0-: Universal Serial Bus 2.0 Port #0 differential pair (directly managed by i.MX 93 USB Host Controller core #1).

USB0_EN_OC#: Power Enable and over current monitoring function. Active Low Output signal, +3.3V_ALW electrical level with a 10kΩ pull-up resistor. Refer to SMARC® 2.1 Specification for over current operation information.

The USB0 port is directly managed by i.MX 93 USB Host Controller core #1 and can be used for serial download driving FORCE_RECOV# low.

Please take note that the OTG functionality on this port is not supported at runtime, USB0 must be set to work as Client or Host at kernel compile time.

USB1+/ USB1-: Universal Serial Bus Port 2.0 #1 differential pair.

USB1_EN_OC#: Power Enable and over current monitoring function. Active Low Output signal, +3.3V_ALW electrical level with a 10kΩ pull-up resistor. Refer to SMARC® 2.1 Specification for OC operation information.

USB2+/USB2-: Universal Serial Bus Port 2.0 #2 differential pair.

USB2_EN_OC#: Power Enable and over current monitoring function. Active Low Output signal, +3.3V_ALW electrical level with a 10kΩ pull-up resistor. Refer to SMARC® 2.1 Specification for OC operation information.

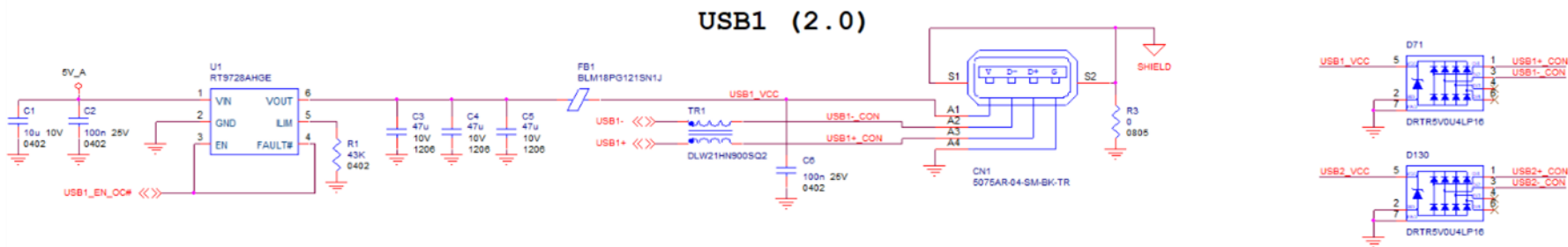
USB3+/USB3-: Universal Serial Bus Port 2.0 #3 differential pair.

USB3_EN_OC#: Power Enable and over current monitoring function. Active Low Output signal, +3.3V_ALW electrical level with a 10kΩ pull-up resistor. Refer to SMARC® 2.1 Specification for OC operation information.

USB4+/USB4-: Universal Serial Bus Port 2.0 #4 differential pair.

USB4_EN_OC#: Power Enable and over current monitoring function. Active Low Output signal, +3.3V_ALW electrical level with a 10kΩ pull-up resistor. Refer to SMARC® 2.1 Specification for OC operation information.

For EMI/ESD protection, common mode chokes on USB data lines, and clamping diodes on USB data and voltage lines, are also needed. Switch with settable current limit on power lines are recommended.



3.2.2.10 Gigabit Ethernet signals

Gigabit Ethernet interfaces are realized on the module using two Realtek RTL8211 Gigabit Ethernet transceivers, which are interfaced to NXP i.MX 93 processor through RGMII interface.

Here following the signals involved in Gigabit Ethernet #0 management:

GBE0_MDIO+/GBE0_MDIO-: Media Dependent Interface (MDI) Transmit/Receive differential pair

GBE0_MDII+/GBE0_MDII-: Media Dependent Interface (MDI) Transmit differential pair

GBE0_MDI2+/GBE0_MDI2-: Media Dependent Interface (MDI) Transmit differential pair

GBE0_MDI3+/GBE0_MDI3-: Media Dependent Interface (MDI) Transmit differential pair

GBE0_LINK_ACT#: Ethernet controller activity indicator. Active Low Output signal, +3.3V_ALW electrical level

GBE0_LINK100#: Ethernet controller 100Mbps link indicator. Active Low Output signal, +3.3V_ALW electrical level

GBE0_LINK1000#: Ethernet controller 1Gbps link indicator. Active Low Output signal, +3.3V_ALW electrical level

GBE0_SDP: Software defined pin, directly managed by TI Gigabit Ethernet PHY transceiver #0. Bidirectional signal, +3.3V_ALW electrical level.

Here following the signals involved in Gigabit Ethernet #1 management:

GBE1_MDIO+/GBE1_MDIO-: Media Dependent Interface (MDI) Transmit/Receive differential pair

GBE1_MDII+/GBE1_MDII-: Media Dependent Interface (MDI) Transmit differential pair

GBE1_MDI2+/GBE1_MDI2-: Media Dependent Interface (MDI) Transmit differential pair

GBE1_MDI3+/GBE1_MDI3-: Media Dependent Interface (MDI) Transmit differential pair

GBE1_LINK_ACT#: Ethernet controller activity indicator. Active Low Output signal, +3.3V_ALW electrical level

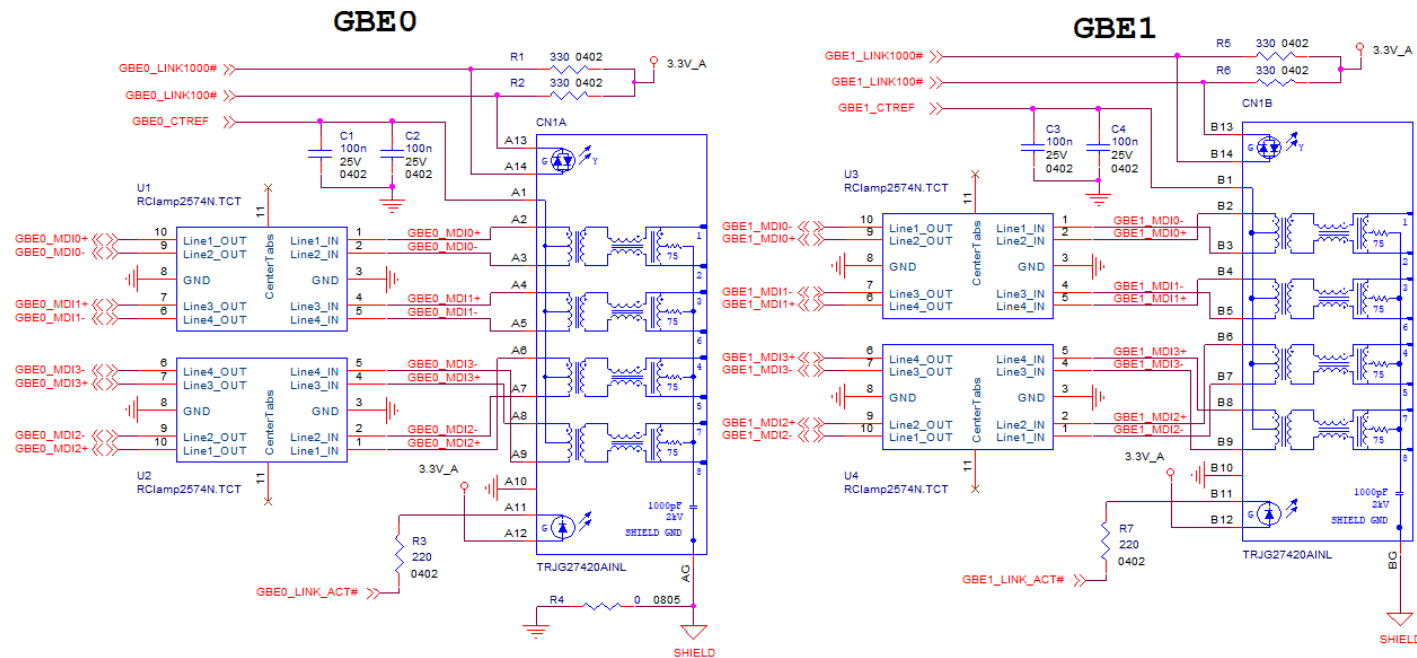
GBE1_LINK100#: Ethernet controller 100Mbps link indicator. Active Low Output signal, +3.3V_ALW electrical level

GBE1_LINK1000#: Ethernet controller 1Gbps link indicator. Active Low Output signal, +3.3V_ALW electrical level

GBE1_SDP: Software defined pin, directly managed by TI Gigabit Ethernet PHY transceiver #1. Bidirectional signal, +3.3V_ALW electrical level.

Please refer to the following schematics as an example of connection of Ethernet interface on the carrier board, with TVS diodes specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD. In this example, it is also present GBE_CTREF signal connected on pin #2 of the RJ-45 connector. TI Gigabit Ethernet PHY transceiver, however, doesn't need the analog powered centre tap, therefore the signal GBE_CTREF is not available on SMARC® connector.

Please notice that if just a FastEthernet (i.e. 10/100 Mbps) is needed, then only MDI0 and MDI1 differential lanes are necessary, for both Gigabit Ethernet interfaces



3.2.2.11 CAN interface signals

Two available CAN interfaces signals are directly managed by the i.MX 93 processor.

CANO_TX: CAN Transmit Output for CAN Bus Channel 0. +1.8V_RUN electrical voltage level signal with a 2k2Ω pull-up resistor

CANO_RX: CAN Receive Input for CAN Bus Channel 0. +1.8V_RUN electrical voltage level signal with a 2k2Ω pull-up resistor

CANI_TX: CAN Transmit Output for CAN Bus Channel 1. +1.8V_RUN electrical voltage level signal with a 2k2Ω pull-up resistor

CAN1_RX: CAN Receive Input for CAN Bus Channel 1. +1.8V_RUN electrical voltage level signal with a 2k2Ω pull-up resistor

Please consider that it is not possible to connect the SMARC® CAN interface to any CAN Bus directly, it is necessary to integrate a CAN Bus Transceiver in the Carrier board.

3.2.2.12 Watchdog

WDT_TIME_OUT#: Watchdog timer Output. +1.8V_RUN electrical level

3.2.2.13 Miscellaneous signals

GPIO0 / CAM0_PWR#: General Purpose I/O #0, +1.8V_RUN electrical level

GPIO1 / CAM1_PWR#: General Purpose I/O #1, +1.8V_RUN electrical level

GPIO2 / CAM0_RST#: General Purpose I/O #2, +1.8V_RUN electrical level

GPIO3 / CAM1_RST#: General Purpose I/O #3, +1.8V_RUN electrical level

GPIO4 / HDA_RST#: General Purpose I/O #4, +1.8V_RUN electrical level

GPIO5 / PWM_OUT: General Purpose I/O #5, +1.8V_RUN electrical level

GPIO6 / TACHIN: General Purpose I/O #6, +1.8V_RUN electrical level

GPIO7: General Purpose I/O #7, +1.8V_RUN electrical level

GPIO8: General Purpose I/O #8, +1.8V_RUN electrical level

GPIO9: General Purpose I/O #9, +1.8V_RUN electrical level

GPIO10: General Purpose I/O #10, +1.8V_RUN electrical level

GPIO11: General Purpose I/O #11, +1.8V_RUN electrical level

GPIO12: General Purpose I/O #12, +1.8V_RUN electrical level

GPIO13: General Purpose I/O #13, +1.8V_RUN electrical level

3.2.2.14 Management pins

According to the SMARC® specifications, the input pins listed below are all Active Low, meant to be driven by open drain devices on the carrier board:

VIN_PWR_BAD#: Power Bad indication signal from the Carrier Board

CARRIER_PWR_ON: Power On. Command to the Carrier Board. Output, +1.8V_RUN electrical level

CARRIER_STBY#: Stand By command to the Carrier Board. Output, +1.8V_RUN electrical level

RESET_OUT#: General Purpose Reset. Output, +1.8V_RUN electrical level

RESET_IN#: General Purpose Reset. Input, +3.3V_RUN electrical level

POWER_BTN#: Power Button. Input, +3.3V_RUN electrical level

SLEEP#: Sleep indicator from Carrier board. Input, +3.3V_RUN electrical level (Standby not supported)

LID#: LID Switch. Input, +3.3V_RUN electrical level

BATLOW#: Battery Low indication signal from the Carrier Board. Input, +3.3V_RUN electrical level

CHARGING#: Battery Charging Input Signal from the Carrier Board. Input, +3.3V_RUN electrical level

CHARGER_PRSENT#: Battery Charger Present input from the Carrier Board. Input, +3.3V_RUN electrical level

TEST#: Held low by Carrier to invoke Module vendor specific test function(s). Input, +3.3V_RUN electrical level with a 10k Ω pull-up resistor

SMB_ALERT_IV8#: SM Bus Alert# (interrupt) signal. Input, +1.8V_RUN electrical level with a 2k2 Ω pull-up resistor

3.2.2.15 Boot Select

The following signals are active low and driven by open drain circuitry on the carrier board.

BOOT_SEL0#: Boot Device Selection #0. Input, +1.8V_RUN electrical level with a 10k Ω pull-up resistor

BOOT_SEL1#: Boot Device Selection #1. Input, +1.8V_RUN electrical level with a 10k Ω pull-up resistor

BOOT_SEL2#: Boot Device Selection #2. Input, +1.8V_RUN electrical level with a 10k Ω pull-up resistor

FORCE_RECOV#: Force recovery Mode. Input, +1.8V_RUN electrical level with a 10k Ω pull-up resistor

Chapter 4. Appendices



SOM-SMARC-MX93

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4.1 SoC to Connector Pinout

Some of the signals available on the SMARC® Edge Connector can be reprogrammed to implement different functionalities, according to the i.MX 93 pin-multiplexing possibilities.

In this table is presented the list of connector signals which are connected to the SoC with the corresponding SoC pad and name. Consult the i.MX 93 documentation for the multiplexing capabilities of the listed pads.

SMARC® Golden Finger Connector – CN2							
TOP SIDE				BOTTOM SIDE			
SoC signal	SoC pad	Pin name	Pin nr.	Pin nr.	Pin name	SoC pad	SoC signal
				S1			
			P1	S2			
			P2	S3			
			P3	S4			
			P4	S5	I2C1_SCL	C20	I2C1_SCL
			P5	S6			
			P6	S7	I2C1_SDA	C21	I2C1_SDA
			P7	S8	CSIO_CK+	E10	MIPI_CSII_CLK_P
			P8	S9	CSIO_CK-	D10	MIPI_CSII_CLK_N
			P9	S10			
			P10	S11	CSIO_RX0+	B11	MIPI_CSII_DO_P
			P11	S12	CSIO_RX0-	A11	MIPI_CSII_DO_N
			P12	S13			
			P13	S14	CSIO_RX1+	B10	MIPI_CSII_D1_P
			P14	S15	CSIO_RX1-	A10	MIPI_CSII_D1_N
			P15	S16			
			P16	S17			

			P17	S18		
			P18	S19		
			P19	S20		
			P20	S21		
			P21	S22		
			P22	S23		
			P23	S24		
			P24	S25		
			P25	S26		
			P26	S27		
			P27	S28		
			P28	S29		
			P29	S30		
			P30	S31		
			P31	S32		
			P32	S33		
			P33	S34		
SD2_CMD	Y19	SDIO_CMD	P34	S35		
SD2_CD_B	Y17	SDIO_CD#	P35	S36		
SD2_CLK	AA19	SDIO_CK	P36	S37		
SD2_RESET_B	AA17	SDIO_PWR_EN	P37	S38		
			P38	S39	I2S0_LRCK	G21 SAI1_TXFS
SD2_DATA0	Y18	SDIO_D0	P39	S40	I2S0_SDOUT	H21 SAI1_TXD0
SD2_DATA1	AA18	SDIO_D1	P40	S41	I2S0_SDIN	H20 SAI1_RXD0
SD2_DATA2	Y20	SDIO_D2	P41	S42	I2S0_CK	G20 SAI1_TXC
SD2_DATA3	AA20	SDIO_D3	P42	S43		
GPIO_I008	M20	SPIO_CS0#	P43	S44		
GPIO_I011	N18	SPIO_CK	P44	S45		
GPIO_I009	M21	SPIO_DIN	P45	S46		

GPIO_IO10	N17	SPIO_DO	P46	S47			
			P47	S48	I2C3_SCL	Y21	GPIO_IO29
			P48	S49	I2C3_SDA	W20	GPIO_IO28
			P49	S50			
			P50	S51			
			P51	S52			
			P52	S53			
			P53	S54			
			P54	S55			
			P55	S56			
			P56	S57			
			P57	S58			
			P58	S59			
			P59	S60			
USB1_D_P	B14	USB0+	P60	S61			
USB1_D_N	A14	USB0-	P61	S62			
			P62	S63			
			P63	S64			
USB1_ID	C11	USB0_OTG_ID	P64	S65			
			P65	S66			
			P66	S67			
			P67	S68			
			P68	S69			
			P69	S70			
			P70	S71			
			P71	S72			
			P72	S73			
			P73	S74			
			P74	S75			

P75	S76
P76	S77
P77	S78
P78	S79
P79	S80
P80	S81
P81	S82
P82	S83
P83	S84
P84	S85
P85	S86
P86	S87
P87	S88
P88	S89
P89	S90
P90	S91
P91	S92
P92	S93
P93	S94
P94	S95
P95	S96
P96	S97
P97	S98
P98	S99
P99	S100
P100	S101
P101	S102
P102	S103
P103	S104

			P104	S105			
			P105	S106			
			P106	S107			
			P107	S108			
			P108	S109			
			P109	S110			
			P110	S111			
			P111	S112			
			P112	S113			
			P113	S114			
			P114	S115			
			P115	S116			
			P116	S117			
			P117	S118			
			P118	S119			
			P119	S120			
			P120	S121			
			P121	S122			
			P122	S123			
			P123	S124			
			P124	S125	LVDS0_TX0_P	B5	LVDS_D0_P
			P125	S126	LVDS0_TX0_N	A5	LVDS_D0_N
			P126	S127			
			P127	S128	LVDS0_TX1_P	B4	LVDS_D1_P
			P128	S129	LVDS0_TX1_N	A4	LVDS_D1_N
GPIO_IO00	J21	SERO_TX	P129	S130			
GPIO_IO01	J20	SERO_RX	P130	S131	LVDS0_TX2_P	B2	LVDS_D2_P
GPIO_IO03	K21	SERO_RTS#	P131	S132	LVDS0_TX2_N	A2	LVDS_D2_N
GPIO_IO02	K20	SERO_CTS#	P132	S133			

			P133	SI34	LVDS0_CK+	B3	LVDS_CLK_P
UART1_TXD	E21	SER1_TX	P134	SI35	LVDS0_CK-	A3	LVDS_CLK_N
UART1_RXD	E20	SER1_RX	P135	SI36			
GPIO_IO04	L17	SER2_TX	P136	SI37	LVDS0_TX3_P	C1	LVDS_D3_P
GPIO_IO05	L18	SER2_RX	P137	SI38	LVDS0_TX3_N	B1	LVDS_D3_N
GPIO_IO07	L21	SER2_RTS#	P138	SI39	I2C1_SCL	C20	I2C1_SCL
GPIO_IO06	L20	SER2_CTS#	P139	SI40	I2C1_SDA	C21	I2C1_SDA
UART2_TXD	F21	SER3_TX	P140	SI41			
UART2_RXD	F20	SER3_RX	P141	SI42			
			P142	SI43			
PDM_CLK	G17	CANO_TX	P143	SI44			
PDM_BIT_STREMO	J17	CANO_RX	P144	SI45			
GPIO_IO25	V21	CANI_TX	P145	SI46			
GPIO_IO27	W21	CANI_RX	P146	SI47			
			P147	SI48			
			P148	SI49			
			P149	SI50			
			P150	SI51			
			P151	SI52			
			P152	SI53			
			P153	SI54			
			P154	SI55			
			P156	SI56			
			P157	SI57			
				SI58			

4.2 Thermal Design

Highly integrated modules like SOM-SMARC-MX93 offer very high performance within small dimensions. On the other hand, the miniaturization of ICs and the high operating frequencies of the processors lead to high heat generation that must be dissipated in order to maintain the CPU within its allowed temperature range.

The operating temperature specified in the Technical Features of SOM-SMARC-MX93 module indicates the temperature range in which any and all parts of the heat spreader / heat sink must remain, in order for SECO to guarantee functionality. Hence, these numbers do not necessarily indicate the suitable environmental temperature.

The heat spreader is not intended to be a guaranteed standalone cooling system but should be used only as a supplemental means of transferring heat to another dissipation system (i.e. heat sinks, fans, heat pipes etc).

It is the customer's responsibility to design and apply an application-dependent cooling system, capable of ensuring that the heat spreader / heat sink temperature remain within the indicated range of the module.

It is an absolute requirement that the customer, after thorough evaluation of the processor's workload in the actual system application, the system enclosure and consequent air flow/Thermal analysis, accurately study and develop a suitable cooling solution for the assembled system.

SECO can provide SOM-SMARC-MX93 module specific heat spreaders and Thermal Pad, but please remember that their use must be evaluated accurately inside the final system, and that they should be used only as a part of a more comprehensive ad-hoc cooling solutions.

Ordering Code	Description
DM02-00005AP_00	SMARC® HEAT SPREADER: Maury Heat Spreader (PASSIVE)
DT01-00006A_00	SMARC® Thermal Pad: Maury Thermal Gap Filler



Warning!

The thermal solutions available with SECO boards are tested in the commercial temperature range (0-60°C), without housing and inside climatic chamber. Therefore, the customer is suggested to study, develop and validate the cooling solution for his system, considering ambient temperature, processor's workload, utilisation scenarios, enclosures, air flow and so on.

In particular, the heat spreader is not intended to be a cooling system by itself, but only as the standard means for transferring heat to cooler, like heatsinks, cold plate, heat pipes and so on.



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